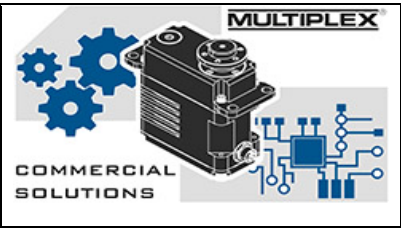




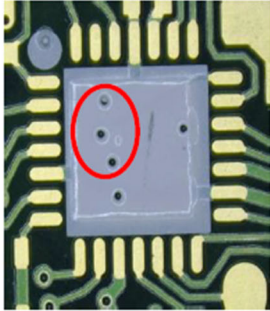
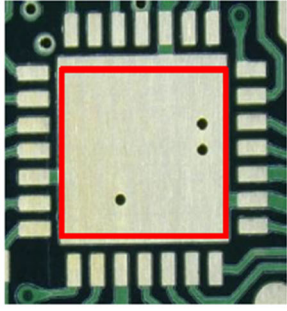
Product Change Notification



TITLE	PCB Pattern Change_240131
DATE	2024.01.31
VALID FROM	The 2nd quarter of 2024
AFFECTED PRODUCT(S)	HSB-9xxx Series, HSB-M9xxx Series, HSR-M9xxx Series
Please note: This change also affect all customized products based on affected products	

CHANGE

- PCB Pattern Change (Via Holes) of HSB Series BLDC Servos.

Before change	After change
You will notice changes to the following parts in the appearance of the PCB.	
 <p>In appearance, the via holes are located on the PCB as shown above, and we applied Silk-Print to block them.</p>	 <p>The PCB pattern change is applied to avoid potential issues. The Silk-Print is no longer applied. (Better workability)</p>

REMARKS

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TOPIC	PCB pattern change
EXPLANATION	By changing the PCB layout, the reflow soldering process under the SMD chip is optimized.
RISK ASSESSMENT	No negative effect to the function or quality of the device
BENEFIT	Improved workability and higher operational reliability.

	Name	Role	Date
Written by	M. Steinmetz	Tech. sales	2024-02-06
Reviewed by	T. Lauber	Documentation	2024-02-06
Approved	Lauber	Technical dept.	2024-02-12

THIS DOCUMENT IS VALID WITHOUT A SIGNATURE

